



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



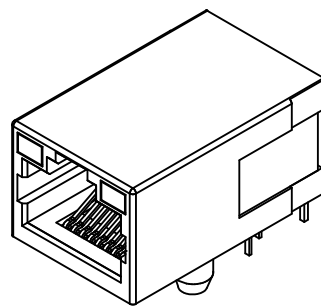
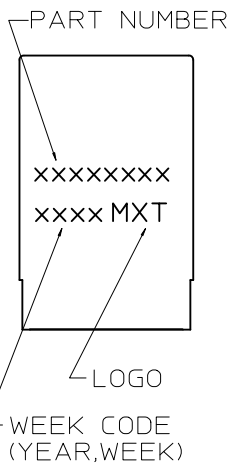
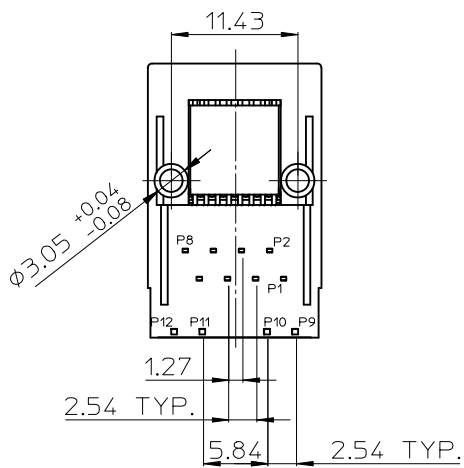
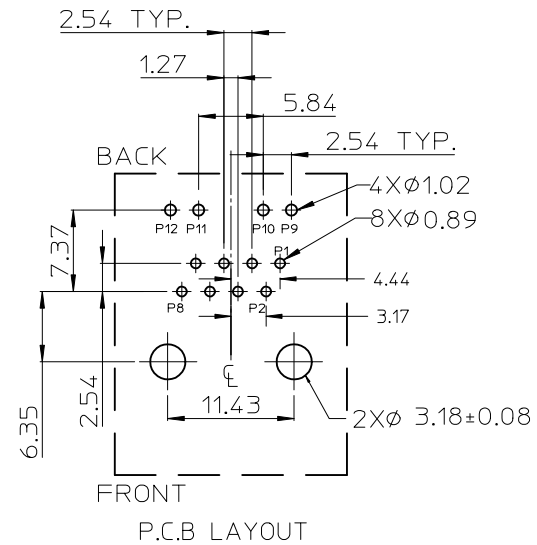
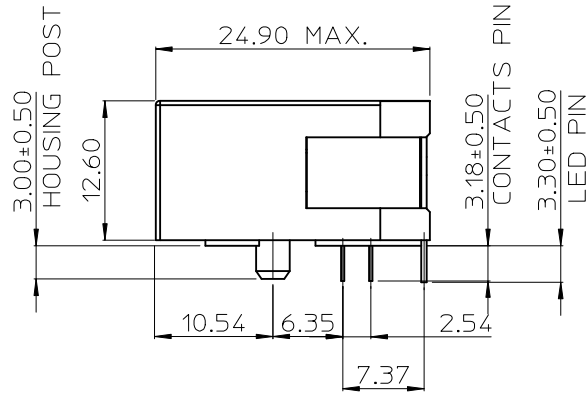
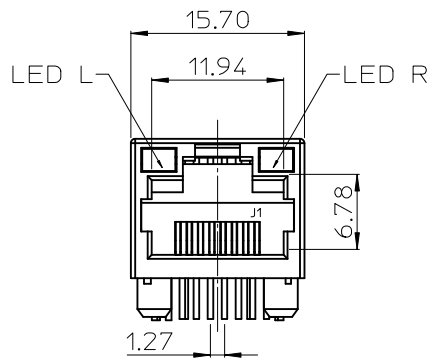
Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





NOTES:

1.MATERIAL:

HOUSING: POLYAMIDE, GLASS FIBER FILLED, UL94-0,COLOR BLACK
 INSERT: POLYAMIDE, GLASS FIBER FILLED, UL94-0,COLOR BLACK
 TERMINAL: PHOSPHOR BRONZE

2.PLATING:

TERMINAL:
 CONTACT AREA: GOLD(Au),THICKNESS=50 MICROINCH/1.27 MICROMETER
 SOLDER TAIL: TIN(Sn),THICKNESS=100 MICROINCH MINIMUM
 UNDER PLATE: NICKEL (Ni).

3.RECOMMENDED PCB THICKNESS: 1.60±0.05

4.PRODUCT SPECIFICATION REFER TO PS-48025-005

5.TEST SUMMARY REFER TO TS-48025-010

6.PACKAGING SPECIFICATION REFER TO PK-48025-001

7.LEAD FREE AND RoHS COMPLIANT PRODUCT.

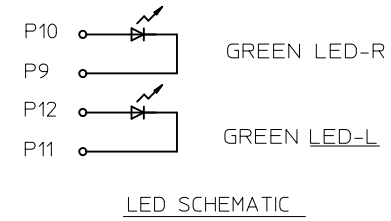
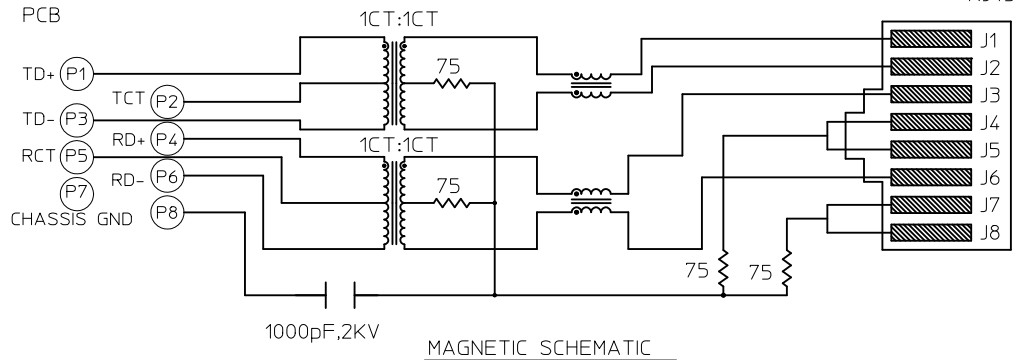
| | | | | | | | | |
|--|-------------------------------|--|--|--|----------------------------|---|------------------------|--|
| RELEASED EC NO: SH2012-0381 DRWNR: L109 2012/05/14 CHKD: APPR: RZHANG 2012/06/22 | QUALITY SYMBOLS ▽=0 ▽=0 | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | SCALE 1:1 | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION | |
| | | | | DRAWN BY LINDA | DATE 2006/08/08 | TITLE MODULAR JACK WITH LED, INTEGRATED MAGNETICS WITHOUT GROUND SHIELD | | |
| | | | | CHECKED BY ALLEN LIN | DATE 2006/08/10 | | | |
| | | | | APPROVED BY ERICK LAN | DATE 2006/08/10 | | | |
| | | MATERIAL NO. 48025-2090 | | DOCUMENT NO. SD-48025-010 | SHEET NO. 1 OF 2 | | | |
| | | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | |

MAGNETIC ELECTRICAL SPECIFICATIONS:

- 1.0 TURNS RATIO:(P4-P5-P6):(J3-J6):1CT:1CT
(P3-P2-P1):(J1-J2):1CT:1CT
- 2.0 INDUCTANCE:(P4-P6):350uH MIN. @0.1V,100KHz,8mA DC Bias.
(P3-P1):350uH MIN. @0.1V,100KHz,8mA DC Bias.
- 3.0 LEAKAGE INDUCTANCE:P6-P5-P4(WITH J6 AND J3 SHORT):0.3 MAX.@1MHZ.
P3-P2-P1(WITH J2 AND J1 SHORT):0.3 MAX.@1MHZ.
- 4.0 INTERWINDING CAPACITANCE:(P6,P5,P4) TO (J6,J3):30pf MAX @1MHZ.
(P3,P2,P1) TO (J2,J1):30pf MAX @1MHZ.
- 5.0 DC RESISTANCE:(J6-J3)=(J2-J1):1.3 ohms Max.
- 6.0 RETURN LOSS:(P4-P6)(P1-P3)
1MHz TO 30MHz:18dB min.
30MHz TO 80MHz:12dB min.
NOTE:100 OHMS CONNECTED TO (J2-J1) OR (J3-J6).
- 7.0 HI-POT:(J1,J2) TO (P1,P3):1500 VAC OR 2250 VDC.
(J3,J6) TO (P4,P6):1500 VAC OR 2250 VDC.
- 8.0 INSERTION LOSS:1 dB MAX.
100KHz TO 100MHz.
- 9.0 CROSS TALK:1-100 MHz:30 dB MIN.
- 10.0 COMMON TO COMMON MODE REJECTION:1MHz TO 100MHz:35 dB MIN.

LED ELECTRICAL SPECIFICATION

| PARAMETER | GREEN (TYP.) | UNITS | TEST CONDITIONS |
|-------------------|--------------|-------|-----------------|
| POWER DISSIPATION | 105 | mW | |
| REVERSE VOLTAGE | 5 | V | |
| PEAK WAVELENGTH | 565 | nm | IF=20mA |
| FORWARD VOLTAGE | 2.2 MAX.=2.5 | V | IF=20mA |



| | | | | | | | | |
|---|-----------------|---------------------------------------|--------|----------------------------|--|--------------------|---|------------------------|
| RELEASED IEC NO: SH2012-0381 DRWNR: L109 2012/05/14 CHKD: APPR: RZHANG 2012/06/22 | QUALITY SYMBOLS | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | | SCALE 1:1 | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION |
| | ▼=0 ▽=0 | 4 PLACES | ± --- | ± --- | DRAWN BY LINDA | DATE 2006/08/08 | TITLE MODULAR JACK WITH LED, INTEGRATED MAGNETICS WITHOUT GROUND SHIELD molex DOCUMENT NO. SD-48025-010 SHEET NO. 2 OF 2 | |
| | | 3 PLACES | ± --- | ± --- | CHECKED BY ALLEN LIN | DATE 2006/08/10 | | |
| | | 2 PLACES | ± 0.25 | ± --- | APPROVED BY ERICK LAN | DATE 2006/08/10 | | |
| | 1 PLACE | ± 0.25 | ± --- | MATERIAL NO. 48025-2090 | | | | |
| | | 0 PLACE | ± | ± | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | |